

3.2x1.6 x1.8mm Dome Lens Chip LED

OSXX120641E

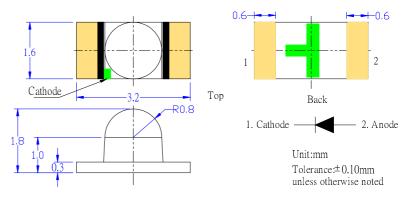
■Features

- · Single chip
- · Super high brightness of surface mount LED
- Compact package outline
 (L x W x T) of 3.2mm x 1.6mm x1.8mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

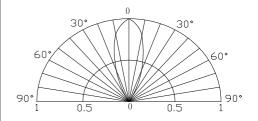
■Outline Dimension



■Absolute Maximum Rating

Item	Cromb of	Val	Unit		
nem	Symbol	B5/G5	G8/Y5/O5/R5	Unit	
DC Forward Current	I_{F}	30	30	mA	
Pulse Forward Current#	I_{FP}	100	100	mA	
Reverse Voltage	V_R	5	5	V	
Power Dissipation	P_D	108	78	mW	
Operating Temperature	Topr	-40 ~ +85			
Storage Temperature	Tstg	-40~ +85			
Lead Soldering Temperature	Tsol	260°C/10sec			

Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25)	C)	
(\mathbf{M})		1

(Ta=25°C)

			$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)			2θ1/2(deg)			
Part Number	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
					I _F =20mA			I _F =20mA						
OSB5120641E	Blue	B5		2.8	-	3.6	10	650	850	-	460	465	475	35
OSG5120641E	True Green	G5		2.8	-	3.6	10	2000	2500	-	515	520	530	35
OSG8120641E	Yellow Green	G8		1.8	-	2.6	10	100	150	-	565	570	575	35
OSY5120641E	Yellow	Y5		1.8	-	2.6	10	300	500	-	585	590	595	35
OSR5120641E	Red	R5		1.8	-	2.6	10	650	850	-	615	620	630	35

^{*1} Tolerance of measurements of chromaticity coordinate is $\pm 10\%$

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^{*2} Tolerance of measurements of dominant wavelength is ± 1 nm

^{*3} Tolerance of measurements of luminous intensity is ±15%

^{*4} Tolerance of measurements of forward voltage is±0.1V



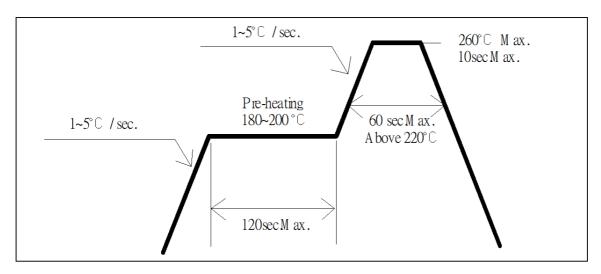
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■ Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature Soldering time	350°C Max.		
Dipping Time	10 sec. Max.		3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.





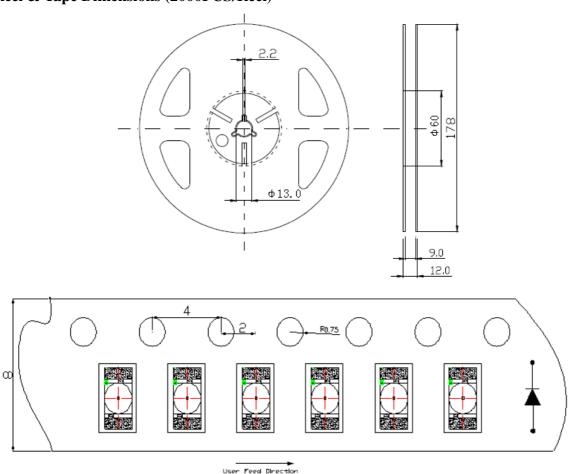




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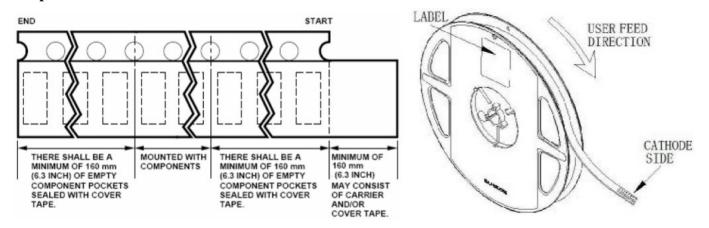
■Packaging

1. Reel & Tape Dimensions (2000PCS/Reel)



Notes: All dimensions are in millimeters

2. Tape leader & Trailer Dimensions & Reel











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■ Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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